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July 2013

FSUSB45 — High-Speed USB2.0 (480Mbps) Switch with Dedicated Charger Port Detect

Features

- Low On Capacitance: 7.0 pF Typical
 Low On Resistance: 3.9 Ω Typical
- Low Power Consumption: 1 μA Maximum
 - 15 μA Maximum I $_{CCT}$ over an Expanded Voltage Range (V $_{IN}$ =1.8 V, V $_{CC}$ =4.3 V)
- Wide -3 db Bandwidth: > 720 MHz
- Packaged in:
 - 10-Lead MicroPak™ (1.6 x 2.1 mm)
 - 10-Lead UMLP (1.4 x 1.8 mm)
- 8 kV ESD Rating, >16 kV Power/GND ESD Rating
- Power-Off Protection on All Ports When V_{CC=}0 V
 - D+/D- Pins Tolerate up to 5.25 V

Applications

- Cell Phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

IMPORTANT NOTE:

For additional performance information, please contact analogswitch@fairchildsemi.com.

Description

The FSUSB45 is a bi-directional, low-power, two-port, High-Speed, USB2.0 switch. Configured as a double-pole, double-throw (DPDT) switch, it is optimized for switching between two HS (480 Mbps) sources or an HS source and a Full-Speed (12 Mbps) source.

The FSUSB45 is compatible with the requirements of USB2.0 and features an extremely low on capacitance (C_{ON}) of 7.0 pF. The wide bandwidth of this device (720 MHz) exceeds the bandwidth needed to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The FSUSB45 contains special circuitry on the switch I/O pins for applications where the V_{CC} supply is powered-off (V_{CC} =0), which allows the device to withstand an over-voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the SEL pin is lower than the supply voltage (V_{CC}). This feature is especially valuable to mobile applications, such as cell phones, allowing for direct interface with the general-purpose I/Os of the baseband processor. An additional feature is the detection of the 1,1 state on D+/D- to signal an interrupt (INT) to the processor when entering a dedicated charging port mode of operation.

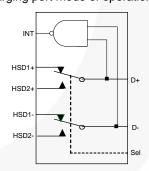


Figure 1. Analog Symbol

Ordering Information

Part Number	Top Mark	Operating Temperature Range	Package
FSUSB45L10X	JA	JA -40 to +85°C 10-Lead, MicroPak™ 1.6 x 2.1 mm, JEI	
FSUSB45UMX	JB	-40 to +85°C	10-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.4 x 1.8 mm

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Pin Assignments

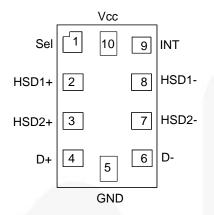


Figure 2. Pad Assignments for MicroPak (Top Through View)

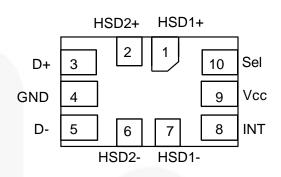


Figure 3. Pin Assignments for UMLP (Top Through View)

Pin Definitions

MicroPak™ Pin#	UMLP Pin #	Name	Description
9	8	INT	Interrupt Signaling Output Pin
1	10	Sel	Switch Select
4, 6	3, 5	D+, D-	USB Data Bus
2, 3, 7, 8	1, 2, 6, 7	HSDn+, HSDn-	Multiplexed Source Inputs
5	4	GND	Ground

Truth Table

Sel	Switch Connection	INT Output
L	D+, D-=HSD1+, HSD1-	LOW
Н	D+, D-=HSD2+, HSD2-	HIGH

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
V _{CC}	Supply Voltage		-0.5	+5.5	V
V _{CNTRL}	DC Input Voltage (S) ⁽¹⁾		-0.5	Vcc	V
V_{SW}	DC Switch I/O Voltage ⁽¹⁾	-0.50	5.25	V	
I _{IK}	DC Input Diode Current	-50		mA	
I _{OUT}	DC Output Current			50	mA
T _{STG}	Storage Temperature		-65	+150	°C
		All Pins		7	
ESD	Human Body Model, JEDEC: JESD22-A114	I/O to GND	/	8	kV
E3D		Power to GND		16	ĸv
	Charged Device Model, JEDEC: JESD22-C10		2		

Note:

1. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
Vcc	Supply Voltage	3.0	4.3	V
V _{CNTRL} ⁽²⁾	Control Input Voltage (Sel)	0	V _{CC}	V
V _{SW}	Switch I/O Voltage	-0.5	Vcc	V
T _A	Operating Temperature	-40	85	°C

Note:

2. The control input must be held HIGH or LOW; it must not float.

DC Electrical Characteristics

All typical value are at 25°C, V_{CC}=3.3 V unless otherwise specified.

Symbol	Davamatar	Conditions	V 00	T _A =- 40°C to +85°C			Units
Symbol	Parameter	Conditions	V _{cc} (V)	Min.	Тур.	Max.	Units
V _{IK}	Clamp Diode Voltage	I _{IN} =-18 mA	3.0			-1.2	V
V	Input Voltage High		3.0 to 3.6	1.3			V
V _{IH}	Input Voltage High		4.3	1.7			V
VIL	Input Voltage Low		3.0 to 3.6			0.5	V
V IL	Input Voltage Low		4.3			0.7	V
V	Он Output Voltage High I _{OH} =-2 mA	I 2 mA	3.0 to 3.6	2.4			V
VOH		IOH=-Z IIIA	4.3	2.4			V
\/	Output Voltage Low	I −2 m \	3.0 to 3.6			0.25	V
V _{OL}		I _{OL} =2 mA	4.3			0.25	V
I _{IN}	Control Input Leakage	V _{SW} =0 to V _{CC}	4.3	-1		1	μΑ
I _{NC(OFF)} , I _{NO(OFF)}	Off State Leakage HSD1n or HSD2n=0 V, 3.6 V or floating, D+/-=0 or 3.6 V		4.3	-2		2	μΑ
I _{Dn(ON)}	ON State Leakage	HSD1n or HSD2n=0 V, 3.6 V or floating, D+/-=0 or 3.6 V		-2		2	μΑ
l _{OFF}	Power-Off Leakage Current (All I/O Ports)	V _{SW} =0 V to 4.3 V, V _{CC} =0 V, Figure 5	0	-2	V	2	μΑ
Ron	HS Switch On Resistance ⁽³⁾	V _{SW} =0.4 V, I _{ON} =-8 mA, Figure 4	3.0		3.9	6.5	Ω
ΔR_{ON}	HS Delta R _{ON} ⁽⁴⁾ V _{SW} =0.4 V, I _{ON} =-8 mA		3.0		0.65		Ω
Icc	Quiescent Supply Current	ent Supply Current V _{CNTRL} =0 or V _{CC} , I _{OUT} =0				1.0	μΑ
	Increase in I _{CC} Current per	V _{CNTRL} =2.6 V, V _{CC} =4.3 V	4.3			10.0	μΑ
Ісст	Control Voltage and V _{CC}	V _{CNTRL} =1.8 V, V _{CC} =4.3 V	4.3	- //		20.0	μΑ

Notes:

- Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).
- 4. Guaranteed by characterization.

AC Electrical Characteristics

All typical value are for V_{CC} =3.3 V at 25°C unless otherwise specified.

Symbol	Doromotor	Conditions	V 00	T _A =- 40 to +85°C			Units
Symbol	Parameter	Conditions	V _{cc} (V)	Min.	Тур.	Max.	Units
t _{ON}	Turn-On Time, S to Output	R_L =50 Ω , C_L =5 pF, V_{SW} =0.8 V, Figure 6, Figure 7	3.0 to 3.6		13	30	ns
t _{OFF}	Turn-Off Time, S to Output	R_L =50 Ω , C_L =5 pF, V_{SW} =0.8V, Figure 6, Figure 7	3.0 to 3.6		12	25	ns
t _{PD}	Propagation Delay ⁽⁵⁾	C_L =5 pF, R_L =50 Ω , Figure 6, Figure 8	3.3		0.25		ns
t _{BBM}	Break-Before-Make	R_L =50 Ω , C_L =5 pF, V_{SW1} = V_{SW2} =0.8 V, Figure 12	3.0 to 3.6	2.0		6.5	ns
t _{PLH/HL}	INT Propagation Delay ⁽⁵⁾	$R_L=50 \Omega$, $C_L=5 pF$	3.0 to 3.6			10	ns
O _{IRR}	Off Isolation	R _L =50 Ω , f=24 0MHz, Figure 14	3.0 to 3.6		-30		dB
Xtalk	Non-Adjacent Channel Crosstalk	R_L =50 Ω, f=240 MHz, Figure 15	3.0 to 3.6		-45		dB
BW	-3 db Bandwidth	R _L =50 Ω, C _L =0 pF, Figure 13	3.0 to 3.6		720		MHz
DVV	-3 ub balluwiuili	R_L =50 Ω, C_L =5 pF, Figure 13	3.0 10 3.0		550		MHz

Note:

USB Hi-Speed-Related AC Electrical Characteristics

Cumbal	Darameter	Conditions	V (V)	T _A =- 40 to +85°C			Units
Symbol	Parameter	Conditions	V _{cc} (V)	Min.	Тур.	Max.	Units
t _{SK(P)}	Skew of Opposite Transitions of the Same Output ⁽⁶⁾	C_L =5 pF, R_L =50 Ω , Figure 9	3.0 to 3.6	l l	20		ps
tJ	Total Jitter ⁽⁶⁾	R _L =50 Ω , C _L =5 pF, t _R =t _F =500 ps (10-90%) at 480 Mbps (PRBS=2 ¹⁵ – 1)	3.0 to 3.6	1	200		ps

Note:

Capacitance

Symbol	Parameter	Conditions		T _A =- 40 to +85°C		
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
C _{IN}	Control Pin Input Capacitance	V _{CC} =0		1.5	11	pF
C _{OUT}	INT Pin Output Capacitance	V _{CC} =0		2.5		pF
Con	D+/D- On Capacitance	V _{CC} =3.3 V, f=1 MHz, Figure 11		7.0	7.9	pF
C _{OFF}	D1n, D2n Off Capacitance	V _{CC} =3.3 V, Figure 10		2.0		pF

^{5.} Guaranteed by characterization.

^{6.} Guaranteed by characterization.

Test Diagrams

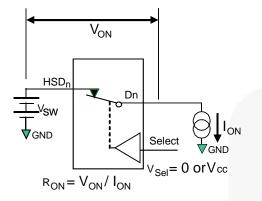
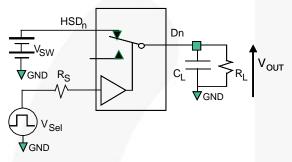


Figure 4. On Resistance



 R_L , R_S , and C_L are functions of the application environment (see AC Tables for specific values) C_L includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load

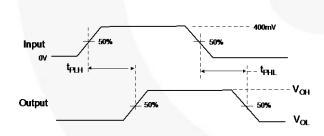


Figure 8. Propagation Delay (t_Rt_F - 500ps)

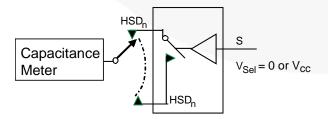


Figure 10. Channel Off Capacitance

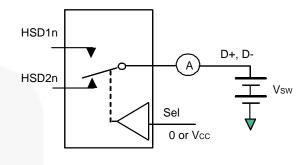


Figure 5. Off/On Leakage

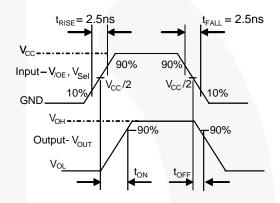


Figure 7. Turn-On / Turn-Off Waveforms

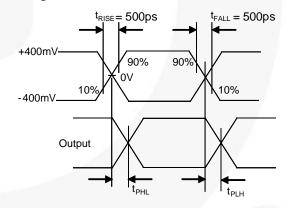


Figure 9. Intra-Pair Skew Test t_{SK(P)}

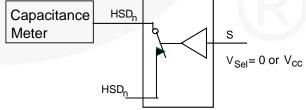


Figure 11. Channel On Capacitance

Test Diagrams (Continued)

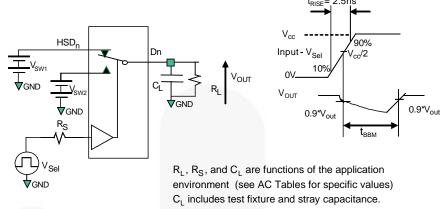


Figure 12. Break-Before-Make Interval Timing

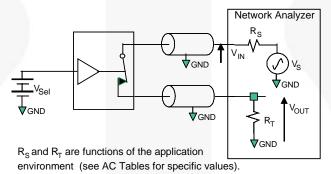
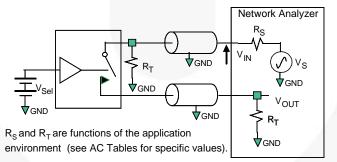
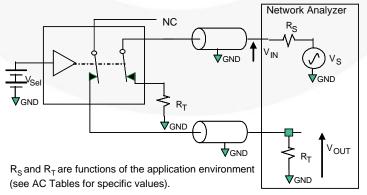


Figure 13. Bandwidth



Off isolation = 20 Log (V_{OUT} / V_{IN})

Figure 14. Channel Off Isolation



Crosstalk = 20 Log (V_{OUT} / V_{IN})

Figure 15. Non-Adjacent Channel-to-Channel Crosstalk

Physical Dimensions

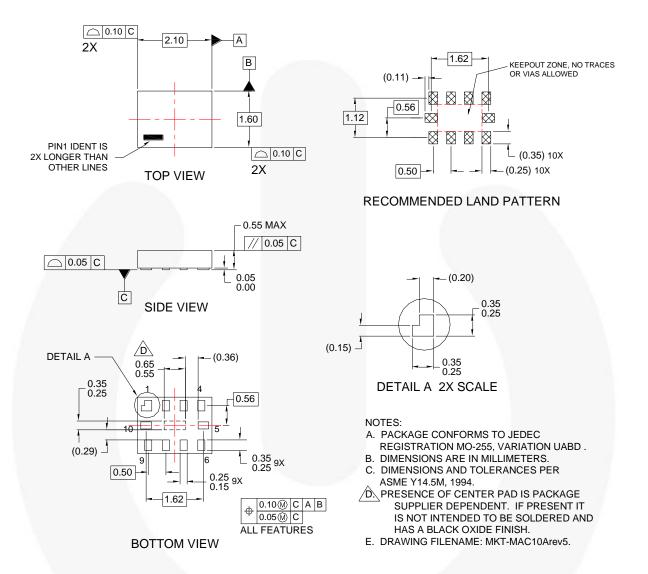


Figure 16. 10-Lead MicroPak™

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Physical Dimensions 0.10 C - 1.40 2X (9X) 1.70 0.563 0.663 1.80 PIN#1 IDENT 2.10 0.10 C 0.40 -**TOP VIEW** 2X (10X)0.225 → RECOMMENDED 0.10 C 0.55 MAX. (0.15)LAND PATTERN 9X 0.08 C 0.45 **SEATING** 0.55 C 0.05 **PLANE** 0.00 SIDE VIEW 0.40 0.35₋(9X) 1.85 0.45 (10X) 0.225 -**OPTIONAL MINIMIAL** 0.40 6 TOE LAND PATTERN DETAIL A NOTES: PIN#1 IDENT A. PACKAGE DOES NOT CONFORM TO (10X) ANY JEDEC STANDARD. B. DIMENSIONS ARE IN MILLIMETERS. 0.10 C A B **BOTTOM VIEW** C. DIMENSIONS AND TOLERANCES PER 0.05 C ASME Y14.5M, 1994. D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY. 0.55 0.45 PACKAGE E. DRAWING FILENAME: MKT-UMLP10Arev5. **EDGE** F. FAIRCHILD SEMICONDUCTOR. **LEAD LEAD** 0.25 **OPTION 2 OPTION 1** 0.15 DETAIL A SCALE: 2X SCALE: 2X SCALE: 2X

Figure 17. 10-Lead Ultrathin Molded Leadless Package (UMLP)

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